© Copyri	al Composition Design to 2005. IPC, Bannock on al and Pan-American of the second secon	burn, Illinois. A	Il rights reserved untions.	nder both	This docume level parts, t	ent is a declara	tion of the encompass	substances es all low	s within the manufacture reveal materials for w	arer listed which the	item. Note: if nanufacturer	the item is an as has engineering	ssembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and N	als and Mfg Information				
Supplier Information														
Company name* Con			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2024-04	2024-04-29			
Contact Name Title - 0			ïtle - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product			roduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Rep			Representative			Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Num	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Dat	e Versior	rsion Manufacturing Site			Weight*	UOM	Unit Type	
	FDMC	FDMC86184 FET 100V		00V 8.5 mOhm PQFN33		2024-04-29			РВВ		70.635765	mg	Each	
Manufacturing Proccess	Information													
Terminal Plating / Grid Array Material Terminal Bas		Terminal Base A	Alloy J	-STD-020 MSI	L Rating	Peak Pro	cess Body '	Temperatu	re Max Time at Peal	k Tempera	ture Numbe	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy			1	1		260		С	30	seco	nds 3			
Comments														
level 1 - maximum time at peak	temperature during s	oldering is 10-3	0 seconds											
For more information regarding	g material composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the ROHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier remedies of the supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	8.097	mg	Supplier	Zinc (Zn)	7440-66-6		0.011	mg
			Supplier	Iron (Fe)	7439-89-6		0.194	mg
			Supplier	Copper (Cu)	7440-50-8		7.892	mg
Die	0.99	mg	Supplier	Silicon (Si)	7440-21-3		0.99	mg
Die Attach Solder	1.989	mg	Supplier	Silver (Ag)	7440-22-4		0.0497	mg
			А	Lead (Pb)	7439-92-1	7a	1.8398	mg
			Supplier	Tin (Sn)	7440-31-5		0.0994	mg
Lead Frame	20.211	mg	Supplier	Zinc (Zn)	7440-66-6		0.026	mg
			Supplier	Iron (Fe)	7439-89-6		0.485	mg
			Supplier	Copper (Cu)	7440-50-8		19.7	mg
Mold Compound-Black	14.236	mg		Proprietary	proprietary data		1.1389	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0712	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		13.0259	mg
Plating	25.1	mg	Supplier	Tin (Sn)	7440-31-5		25.1	mg
Wire Bond	0.012765	mg	Supplier	Palladium (Pd)	7440-05-3		0.0003	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0124	mg